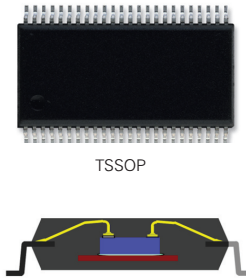


SOP

Small Outline Package

Small Outline Packages (SOP) are industry proven surface mount leadframe packages with a body size and height smaller than DIP packages and a tighter leadframe pitch. They are available in many configurations including MSOP, VSOP, SSOP and TSSOP with body sizes ranging from 150 - 300mils.



TSSOP

Highlights

- Higher density leadframe
- Multi-die and stacked die capability
- 7 - 38 leads
- Cu / Au / Al wire/ribbon options
- Fine BPO/BPP(40um/50um)

Process Highlights

- | | |
|------------------------|----------------------------------|
| • Package Thickness | Minimum of 75um |
| • Die Thickness | Minimum of 60um |
| • Wire | Cu / Au / Al wire/ribbon options |
| • Die Attach Tolerance | +/- 38um |
| • Wire Diameter | 18 - 50um |

Features

- Short signal for high power and electrical performance
- Body sizes from 3x3 to 18.04x7.52
- Pad Pitch from 0.5 to 1.27
- Leadframe strip size: 50x122 to 83x270
- Heatspreader capability

Package Level Reliability

- | | |
|------------------------------|------------------------------|
| • Moisture Sensitivity Level | MSL1/MSL2/MSL3 @260C |
| • Temperature Cycling | -65C to 150C, Dwell = 15 min |
| • Pressure Cooker Test | 121C/100%RH 205 Kpa |
| • THT | 85C, 1000 hrs |
| • HTST | Ta = 150C |

Standard Materials

- Leadframe: Silver Plating, Selective Silver Plating, Surrounding Silver Plating
- Wire: Cu, Au, Al, Al Ribbon
- Epoxy: Film, Conductive, Non-Conductive, Solder Paste, Sinter Paste
- Compound: Green/Non Green Mold Compound
- Lead Finish: Sn Plating

Applications

- Storage
- Communications
- Power Management
- Sensor
- Controller
- Automotive